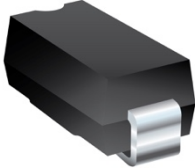


# MATERIAL DECLARATION SHEET



Material Number	1.5SMBJ70A~85A 1.5SMBJ36CA~58CA			
Product Line	Semiconductors			
Compliance Date	2021/01/14			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Dice	Silicon	0.00582	Silicon	7440-21-3	60.1800%	3.589%	5.963%
				Phosphorus	7723-14-0	0.0100%	0.0006%	
				Boron	7440-42-8	0.0100%	0.0006%	
				Nickel	7440-02-0	14.8000%	0.883%	
				Lead	7439-92-1	12.5000%	0.745%	
				Silicon dioxide	7631-86-9	10.0000%	0.596%	
				Aluminum oxide	1344-28-1	2.5000%	0.1491%	
2	High-melting point Solder paste	solder paste	0.00345	Tin	7440-31-5	5.000%	0.177%	3.535%
				Lead	7439-92-1	92.500%	3.270%	
				Silver	7440-22-4	2.500%	0.088%	
3	Lead frame / Leads / Disc	N/A	0.03380	Copper	7440-50-8	99.800%	34.562%	34.631%
				Iron	7439-89-6	0.150%	0.052%	
				Phosphorus	7723-14-0	0.050%	0.017%	
				Silica	60676-86-0	76.000%	41.660%	
4	Molding Compound (Plastic Package Only)	Epoxy material	0.05350	Epoxy resin	29690-82-2	12.000%	6.578%	54.816%
				Phenolic resin	9003-35-4	11.000%	6.030%	
				Carbon black	1333-86-4	1.000%	0.5480%	
				Tin	7440-31-5	100.000%	1.055%	
5	Plating	Matte-Tin	0.00103	Tin	7440-31-5	100.000%	1.055%	1.055%
Total Weight			0.0976 g					

**This Document was updated on: 2021/01/14**

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which are exempted from the requirements. Please see current Certificate of Compliance for exemption(s).